

# PCN#20210927002.1 Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, and additional BOM option for select devices

# **Change Notification / Sample Request**

**Date:** September 28, 2021 **To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) <u>process</u>.

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's previous announcement to close our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

PCN Team SC Business Services

# **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

| DEVICE          | CUSTOMER PART NUMBER |
|-----------------|----------------------|
| SN74HC573APWRG4 | null                 |
| CD74HC238E      | null                 |
| SN74HC157N      | null                 |
| SN74HC595N      | null                 |

Technical details of this Product Change follow on the next page(s).

| PCN Numbe  |   | 02109270  |  |   |   |                        | Date:   | September 28, 202                                       |  |  |  |  |  |  |
|--|---|---|--|---|---|------------------------|---|---|--|--|--|--|--|--|
| Title:Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision,<br>and additional BOM option for select devices                 |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
| Customer Contact:PCN ManagerDept:Quality Services  |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
| Proposed 1 <sup>s</sup>  | <sup>st</sup> Ship Da   | ate: D  | Dec 26, 20   | 021   | Estima<br>Availa  |                        |   | Date provided at sample request.                        |  |  |  |  |  |  |
| Change Typ   | e:  |   |  |   |   |                        |   | · · ·   |  |  |  |  |  |  |
| Assembl  | y Site  |   | Asser  | nbly Pro  | ocess   | $\geq$                 | Asse  | mbly Materials  |  |  |  |  |  |  |
| Design Electrical Specification Mechanical Specification   |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
| Test Site  | ē   |   | Packi  | ng/Ship   | ping/Labeling   |                        | Test  | Process   |  |  |  |  |  |  |
| Wafer Bu   | ump Site  |   | Wafe   | r Bump  | Material  |                        | Wafe  | r Bump Process  |  |  |  |  |  |  |
| 🛛 Wafer Fa   | ab Site   |   | Wafe   | r Fab M   | aterials  |                        | Wafe  | r Fab Process   |  |  |  |  |  |  |
|  |   |   | Part r   | number  | change  |                        |   |   |  |  |  |  |  |  |
|  |   |   |  | PCN I   | Details   |                        |   |   |  |  |  |  |  |  |
| Description  | of Chanc  | ie:   |  |   |   |                        |   |   |  |  |  |  |  |  |
|  |   |   | announce   | e the qu  | alification of a  | a new                  | fab & pr  | ocess technology  |  |  |  |  |  |  |
|  |   |   |  |   |   |                        |   | luct affected section.                                  |  |  |  |  |  |  |
| Construction   |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
|  |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
|  | Curren  | t Fab Site  | e  |   | Current Fab Site Additional Fab Site  |                        |   |   |  |  |  |  |  |  |
| Current Fab         Process         Wafer         Additional         Process         Wafer           Site         Diameter         Fab Site         Diameter |   |   |  |   |   |                        |   |   |  |  |  |  |  |  |
|  | ab Pr   | ocess   | -  | -   |   |                        | Process   |   |  |  |  |  |  |  |
| SFAB   | _   | CMOS  | -  | eter  | Additional<br>Fab Site<br>RFAB  |                        |   | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB   | H   | CMOS  | <b>Diame</b><br>150 r  | eter<br>mm  | Fab Site<br>RFAB  |                        | Process<br>LBC9   |   |  |  |  |  |  |  |
| Site   | H   | CMOS  | <b>Diame</b><br>150 r  | eter<br>mm  | Fab Site<br>RFAB  |                        |   | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a  | H<br>Halso chang  | CMOS<br>ged as a re   | Diame<br>150 r<br>esult of th  | eter<br>nm<br>ne proce  | Fab Site<br>RFAB  |                        | LBC9  | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a  | H<br>Halso chang  | CMOS<br>ged as a re   | Diame<br>150 r<br>esult of th  | eter<br>nm<br>ne proce  | Fab Site<br>RFAB<br>ess change.   | evices                 | LBC9  | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a  | H<br>Halso chang  | CMOS<br>ged as a re<br>be a BOM   | Diame<br>150 r<br>esult of th<br>option in   | eter<br>mm<br>ne proce  | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current   | evices                 | LBC9  | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a  | H<br>Halso chang  | CMOS<br>ged as a re<br>be a BOM<br>Bond   | Diame<br>150 r<br>esult of th<br>option in<br>wire   | eter<br>mm<br>ne proce  | Fab Site<br>RFAB<br>ess change.<br>ed for these de  | evices                 | LBC9  | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,   | H<br>also chang<br>there will   | CMOS<br>ged as a re<br>be a BOM   | Diame<br>150 r<br>esult of th<br>option in<br>wire   | eter<br>mm<br>ne proce  | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current   | evices                 | LBC9<br>:<br>itional                                    | Diameter  |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Reason for (   | H<br>also chang<br>there will<br>Change:  | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete  | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)  | eter<br>mm<br>ne proce<br>ntroduce  | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils   | evices Add 0.8         | LBC9<br>:<br>itional<br>3 mils                          | Diameter<br>300 mm                                      |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Reason for (<br>These change   | H<br>also chang<br>there will<br>Change:<br>es are par                                      | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete  | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p  | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils   | evices Add 0.8         | LBC9<br>:<br>itional<br>3 mils                          | Diameter<br>300 mm<br>150-milimeter                     |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Reason for (<br>These change<br>factories to n   | H<br>also chang<br>there will<br>Change:<br>es are par<br>ewer, mo                          | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete<br>t of our m<br>re efficien                               | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p<br>t manufae                           | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils<br>rransition proc<br>processes and             | evices Add 0.8         | LBC9<br>:<br>itional<br>3 mils                          | Diameter<br>300 mm                                      |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Additionally,<br>Meason for (<br>These change<br>factories to n<br>commitment                              | H<br>also chang<br>there will<br>Change:<br>es are par<br>ewer, mo<br>to produc             | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete<br>t of our m<br>re efficien<br>ct longevity               | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p<br>t manufac<br>y and sup              | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils<br>cransition proc<br>processes and<br>tinuity. | evices Add 0.8 ducts f | LBC9<br>:<br>itional<br>3 mils<br>from our<br>hologies, | Diameter<br>300 mm<br>150-milimeter<br>underscoring our |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Additionally,<br>Meason for (<br>These change<br>factories to n<br>commitment<br>Anticipated               | H<br>also chang<br>there will<br>Change:<br>es are par<br>ewer, mo<br>to produc             | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete<br>t of our m<br>re efficien<br>ct longevity               | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p<br>t manufac<br>y and sup              | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils<br>cransition proc<br>processes and<br>tinuity. | evices Add 0.8 ducts f | LBC9<br>:<br>itional<br>3 mils<br>from our<br>hologies, | Diameter<br>300 mm<br>150-milimeter                     |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Additionally,<br>Meason for (<br>These change<br>factories to n<br>commitment                              | H<br>also chang<br>there will<br>Change:<br>es are par<br>ewer, mo<br>to produc             | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete<br>t of our m<br>re efficien<br>ct longevity               | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p<br>t manufac<br>y and sup              | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils<br>cransition proc<br>processes and<br>tinuity. | evices Add 0.8 ducts f | LBC9<br>:<br>itional<br>3 mils<br>from our<br>hologies, | Diameter<br>300 mm<br>150-milimeter<br>underscoring our |  |  |  |  |  |  |
| Site<br>SFAB<br>The die was a<br>Additionally,<br>Additionally,<br>Meason for (<br>These change<br>factories to n<br>commitment<br>Anticipated               | H<br>also chang<br>there will<br>Change:<br>es are par<br>ewer, mo<br>to produc<br>impact o | CMOS<br>ged as a re<br>be a BOM<br>Bond<br>diamete<br>t of our m<br>re efficient<br>t longevity<br>on Form, I | Diame<br>150 r<br>esult of th<br>option in<br>wire<br>er (Cu)<br>ultiyear p<br>t manufac<br>y and sup<br>Fit, Func | eter<br>mm<br>he proce<br>htroduce<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0<br>0 | Fab Site<br>RFAB<br>ess change.<br>ed for these de<br>Current<br>.96 mils<br>cransition proc<br>processes and<br>tinuity. | evices Add 0.8 ducts f | LBC9<br>:<br>itional<br>3 mils<br>from our<br>hologies, | Diameter<br>300 mm<br>150-milimeter<br>underscoring our |  |  |  |  |  |  |

change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS        | REACH       | Green Status | IEC 62474   |
|-------------|-------------|--------------|-------------|
| 🛛 No Change | 🛛 No Change | 🛛 No Change  | 🛛 No Change |

# Changes to product identification resulting from this PCN:

# Fab Site Information:

| Chip Site | Chip Site Origin<br>Code (20L) | Chip Site Country Code (21L) | Chip Site City |
|-----------|--------------------------------|------------------------------|----------------|
| SH-BIP-1  | SHE                            | USA                          | Sherman        |
| RFAB      | RFB                            | USA                          | Richardson     |

# **Die Rev:**

| Current             | New          |
|---------------------|--------------|
| Die Rev [2P]        | Die Rev [2P] |
| A, E, F, G, H, J, - | Α            |

Sample product shipping label (not actual product label)

| TEXAS<br>INSTRUMENTS<br>MADE IN: Malaysia<br>2DC: 20: | €<br>64 |                 | (1P) SN74LS07NSR<br>(Q) 2000 (D) 0336  |
|---|---------|-----------------|--|
| MSL 2 /260C/1 YEAR<br>MSL 1 /235C/UNLIM               |         |                 | (31T)LOT: 3959047MLA<br>(4W) TKY(1T) 7523483SI2<br>(P)   |
| LBL: 5A (L)TO   | : 1750  | Receiption Cons | (2P) REV: (V) 0033317<br>(20L) <del>CSO. SHE</del> (21L) <del>CCO.USA</del><br>(22L) ASO: MLA (23L) ACO: MYS |

# **Product Affected:**

| CD74HC138E     | SN74HC151N     |                | SN74HC541ANSR   |
|----------------|----------------|----------------|-----------------|
|                |                | SN74HC273NSR   |                 |
| CD74HC138EE4   | SN74HC157N     | SN74HC273PWR   | SN74HC541DBR    |
| CD74HC237E     | SN74HC157NE4   | SN74HC273PWRG4 | SN74HC541N      |
| CD74HC237EE4   | SN74HC165N     | SN74HC367N     | SN74HC541NE4    |
| CD74HC238E     | SN74HC165NE4   | SN74HC373N     | SN74HC541NSR    |
| CD74HC238EE4   | SN74HC166N     | SN74HC373NE4   | SN74HC541PWR    |
| CD74HC259E     | SN74HC174N     | SN74HC373NSR   | SN74HC573AN     |
| CD74HC273E     | SN74HC174NE4   | SN74HC373NSRE4 | SN74HC573ANE4   |
| CD74HC373E     | SN74HC240N     | SN74HC373PWR   | SN74HC573APWR   |
| CD74HC373EE4   | SN74HC240NE4   | SN74HC373PWRE4 | SN74HC573APWRG4 |
| CD74HC374E     | SN74HC240NSR   | SN74HC374N     | SN74HC573NSR    |
| CD74HC377PWR   | SN74HC240NSRE4 | SN74HC374NE4   | SN74HC574DBR    |
| CD74HC377PWRG4 | SN74HC240PWR   | SN74HC374NSR   | SN74HC574DBRG4  |
| CD74HC541E     | SN74HC240PWRG4 | SN74HC374PWR   | SN74HC574N      |
| CD74HC541EE4   | SN74HC241PWR   | SN74HC377N     | SN74HC574NE4    |
| CD74HC541PWR   | SN74HC241PWRE4 | SN74HC377NE4   | SN74HC574NSR    |
| CD74HC573E     | SN74HC251N     | SN74HC377NSR   | SN74HC574PWR    |
| CD74HC573EE4   | SN74HC259N     | SN74HC540N     | SN74HC574PWRE4  |
| CD74HC574E     | SN74HC259NE4   | SN74HC540NE4   | SN74HC574PWRG4  |
| SN74HC138N     | SN74HC273DBR   | SN74HC540NSR   | SN74HC595N      |
| SN74HC138NE4   | SN74HC273N     | SN74HC540PWR   | SN74HC595NE4    |
| SN74HC139N     | SN74HC273NE4   | SN74HC540PWRE4 | SN74HCT573PWR   |
| SN74HC139NE4   |                |                |                 |



## Approve Date 14-Sep-2021

### Qualification Results

## Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name /<br>Condition | Duration | Qual Device:<br><u>SN74HC273NSR</u> | Qual Device:<br><u>SN74HC374NSR</u> | QBS Product<br>Reference:<br><u>CD74HC377PWR</u> | QBS Product<br>Reference:<br><u>SN74HC240PWR</u> | QBS Product<br>Reference:<br><u>SN74HC241PWR</u> | QBS Product<br>Reference:<br><u>SN74HC273PWR</u> | QBS Product<br>Reference:<br><u>SN74HC373PWR</u> |
|------|--------------------------|----------|-------------------------------------|-------------------------------------|--|--|--|--|--|
| CDM  | ESD - CDM                | 1500 V   | 1/3/0                               | -                                   | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
| HBM  | ESD - HBM                | 5000V    | -                                   | -                                   | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
|      |                          |          |                                     |                                     |  |  |  |  |  |

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| 1    | Data Displayed as. Number of lots / Total sample size / Total failed |                                |  |  |  |   |  |   |   |  |  |
|------|--|--------------------------------|--|--|--|---|--|---|---|--|--|
| Туре | Test Name /<br>Condition   | Duration                       | QBS Product<br>Reference:<br><u>SN74HC374PWR</u> | QBS Product<br>Reference:<br><u>SN74HC540PWR</u> | QBS Product<br>Reference:<br><u>SN74HC541PWR</u> | QBS Product<br>Reference:<br><u>SN74HC573APWR</u> | QBS Product<br>Reference:<br><u>SN74HC574PWR</u> | QBS Product<br>Reference:<br><u>SN74HCT573PWR</u> | QBS Process<br>Reference:<br><u>SN74HC S245QPWRQ1</u> |  |  |
| AC   | Autoclave 121C   | 96 Hours                       | -  | -  | -  | -   | -  | -   | 1/77/0  |  |  |
| CDM  | ESD - CDM  | 1500 V                         | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0   | 1/3/0  | 1/3/0   | 1/3/0   |  |  |
| EC   | Electrical<br>Characterization                                       | Per<br>Datasheet<br>Parameters | -  | -  | -  | -   | -  | -   | 3/90/0  |  |  |
| HAST | Biased HAST,<br>130C/85%RH   | 96 Hours                       | -  | -  | -  | -   | -  | -   | 1/77/0  |  |  |
| HBM  | ESD - HBM  | 5000V                          | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0   | 1/3/0  | 1/3/0   | 1/3/0   |  |  |
| HTOL | Life Test, 150C  | 300 Hours                      | -  | -  | -  | -   | -  | -   | 1/77/0  |  |  |
| HTSL | High Temp<br>Storage Bake<br>150C                                    | 1000 Hours                     | -  | -  | -  | -   | -  | -   | 1/45/0  |  |  |
| LU   | Latch-up   | (Per<br>JESD78)                | 1/6/0  | 1/6/0  | 1/6/0  | 1/3/0   | 1/6/0  | 1/6/0   | 1/3/0   |  |  |
| тс   | Temperature<br>Cycle, -65/150C                                       | 500 Cycles                     | -  | -  | -  | -   | -  | -   | 1/77/0  |  |  |
| WBP  | Wire Bond Pull   | Wires                          | -  | -  | -  | -   | -  | -   | 1/30/0  |  |  |

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name /<br>Condition       | Duration                    | QBS Process<br>Reference:<br><u>SN74HC S273QPWRQ1</u> | QBS Package<br>Reference:<br><u>1P8T245NSR</u> | QBS Package<br>Reference:<br><u>SN74HC253NSR</u> | QBS Package<br>Reference:<br><u>SN74HC257NSR</u> | QBS Package<br>Reference:<br><u>ULQ2003AQDRQ1_RLF</u> | QBS Package<br>Reference:<br><u>ULQ2003AQDRQ1_STDLF</u> |
|------|--------------------------------|-----------------------------|---|--|--|--|---|---|
| AC   | Autoclave 121C                 | 96 Hours                    | 1/77/0  | 3/231/0  | -  | -  | 3/231/0   | 3/231/0   |
| CDM  | ESD - CDM                      | 1500 V                      | 1/3/0   | -  | 1/3/0  | -  | -   | -   |
| EC   | Electrical<br>Characterization | Per Datasheet<br>Parameters | No Fails  | -  | -  | -  | No Fails  | -   |
| HAST | Biased HAST,<br>130C/85%RH     | 96 Hours                    | 1/77/0  | -  | -  | -  | -   | 3/231/0   |
| HTOL | Life Test, 150C                | 300 Hours                   | 1/77/0  | -  | -  | -  | -   | -   |
| HTOL | Life Test, 150C                | 408 Hours                   | -   | -  | -  | -  | -   | 3/231/0   |
| HTSL | High Temp Storage<br>Bake 150C | 1000 Hours                  | 1/45/0  | -  | -  | -  | 1/45/0  | 1/45/0  |
| HTSL | High Temp Storage<br>Bake 170C | 420 Hours                   | -   | 3/231/0  | -  | -  | -   | -   |
| LU   | Latch-up                       | (Per JEDC78)                | 1/6/0   | -  | -  | -  | -   | -   |
| тс   | Temperature<br>Cycle, -65/150C | 500 Cycles                  | 1/77/0  | 3/231/0  | -  | -  | 3/231/0   | 3/231/0   |
| WBP  | Wire Bond Pull                 | Wires                       | 1/30/0  | -  | -  | -  | -   | -   |
| WBS  | Wire Bond Shear                | Wires                       | 1/30/0  | -  | -  | -  | -   | -   |

QBS: Qual By Similarity
Qual Device SN74HC374NSR is qualified at LEVEL1-260C
Qual Device SN74HC273NSR is qualified at LEVEL1-260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent TFSL options based on an activation energy of 0.7eV: 125C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green



## Approve Date 14-Sep-2021

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name /<br>Condition                 | Duration                       | Qual Device:<br><u>SN74HC273DBR</u> | QBS Product<br>Reference:<br><u>SN74HC273PWR</u> | QBS Product<br>Reference:<br><u>SN74HC541PWR</u> | QBS Product<br>Reference:<br><u>SN74HC574PWR</u> | QBS Process<br>Reference:<br><u>SN74HCS273QPWRQ1</u> | QBS Package<br>Reference:<br><u>1M16374QDLREP</u> | QBS<br>Package<br>Reference:<br><u>1R16214CDL</u> |
|------|--|--------------------------------|-------------------------------------|--|--|--|--|---|---|
| AC   | Autoclave 121C                           | 96 Hours                       | -                                   | -  | -  | -  | 1/77/0   | 3/231/0   | 3/231/0   |
| CDM  | ESD - CDM                                | 1500 V                         | 1/3/0                               | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | -   | -   |
| ED   | Electrical<br>Characterization           | Per<br>Datasheet<br>Parameters | -                                   | -  | -  | -  | Pass   | Pass  | Pass  |
| HAST | Biased HAST,<br>130C/85%RH               | 96 Hours                       | -                                   | -  | -  | -  | 1/77/0   | -   | -   |
| HBM  | ESD - HBM                                | 5000V                          | -                                   | 1/3/0  | 1/3/0  | 1/3/0  | -  | -   | -   |
| HTOL | Life Test, 150C                          | 300 Hours                      | -                                   | -  | -  | -  | 1/77/0   | -   | -   |
| HTSL | High Temp<br>Storage Bake<br>150C        | 1000 Hours                     | -                                   | -  | -  | -  | 1/45/0   | -   | -   |
| HTSL | High Temp<br>Storage Bake<br>170C        | 420 Hours                      | -                                   | -  | -  | -  | -  | 3/231/0   | -   |
| LU   | Latch-up                                 | (JESD78)                       | -                                   | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | -   | -   |
| PC   | Automotive<br>Preconditioning<br>Level 1 | (Level 1-<br>260C)             | -                                   | -  | -  | -  | No Fails   | -   | -   |
| тс   | Temperature<br>Cycle, -65/150C           | 500 Cycles                     | -                                   | -  | -  | -  | 1/77/0   | 3/231/0   | 4/308/0   |
| WBP  | Bond Pull                                | Wires                          | 1/76/0                              | -  | -  | -  | -  | -   | -   |
| WBS  | Ball Bond Shear                          | Wires                          | 1/76/0                              | -  | -  | -  | -  | -   | -   |

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition       | Duration   | QBS Package Reference:<br><u>BQ77PL900DL</u> | QBS Package Reference:<br><u>SN75976A1DL</u> | QBS Package Reference:<br><u>TLC5920DLR</u> |
|------|-----------------------------|------------|--|--|---|
| AC   | Autoclave 121C              | 96 Hours   | -  | 3/231/0                                      | -   |
| ED   | Electrical Characterization | Per Data   | -  | 1/Pass                                       | -   |
| HTSL | High Temp Storage Bake 170C | 420 Hours  | -  | 3/231/0                                      | -   |
| TC   | Temperature Cycle, -65/150C | 500 Cycles | 3/231/0                                      | 3/231/0                                      | 4/308/0                                     |

- QBS: Qual By Similarity

- Qual Device SN74HC273DBR is qualified at LEVEL1-260C

Qual Device SN74HC273DBR is qualified at LEVEL1-260C
 Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
 Green/Pb-free (SMT) and Green



## Approve Date 14-Sep-2021

#### Qualification Results

#### Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition | Duration     | Qual Device:<br>CD74HC377PWR | Qual Device:<br><u>SN74HC240PWR</u> | Qual Device:<br><u>SN74HC241PWR</u> | Qual Device:<br><u>SN74HC273PWR</u> | Qual Device:<br><u>SN74HC373PWR</u> | Qual Device:<br><u>SN74HC374PWR</u> | Qual Device:<br><u>SN74HC540PWR</u> |
|------|-----------------------|--------------|------------------------------|-------------------------------------|-------------------------------------|-------------------------------------|-------------------------------------|-------------------------------------|-------------------------------------|
| CDM  | ESD - CDM             | 1500 V       | 1/3/0                        | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               |
| HBM  | ESD - HBM             | 5000V        | 1/3/0                        | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               | 1/3/0                               |
| LU   | Latch-up              | (per JESD78) | 1/6/0                        | 1/6/0                               | 1/6/0                               | 1/6/0                               | 1/6/0                               | 1/6/0                               | 1/6/0                               |

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition                 | Duration                             | Qual Device:<br><u>SN74HC541PWR</u> | Qual Device:<br><u>SN74HC573APWR</u> | Qual Device:<br><u>SN74HC574PWR</u> | Qual Device:<br><u>SN74HCT573PWR</u> | QBS Process<br>Reference:<br><u>SN74HC S273QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HCS244QPWRQ1</u> |
|------|---------------------------------------|--------------------------------------|-------------------------------------|--------------------------------------|-------------------------------------|--------------------------------------|---|--|
| AC   | Autoclave 121C                        | 96 Hours                             | -                                   | -                                    | -                                   | -                                    | 1/77/0  | 1/77/0   |
| CDM  | ESD - CDM                             | 1500 V                               | 1/3/0                               | 1/3/0                                | 1/3/0                               | 1/3/0                                | 1/3/0   | 1/3/0  |
| EC   | Electrical<br>Characterization        | Cpk>1.67 Room,<br>hot, and cold test | -                                   | -                                    | -                                   | -                                    | 3/90/0  | 3/90/0   |
| HAST | Biased HAST,<br>130C/85%RH            | 96 Hours                             | -                                   | -                                    | -                                   | -                                    | 1/77/0  | 1/77/0   |
| HBM  | ESD - HBM                             | 5000V                                | 1/3/0                               | 1/3/0                                | 1/3/0                               | 1/3/0                                | 1/3/0   | 1/3/0  |
| HTOL | Life Test, 150C                       | 300 Hours                            | -                                   | -                                    | -                                   | -                                    | 1/77/0  | 1/77/0   |
| HTSL | High Temp Storage<br>Bake 150C        | 1000 Hours                           | -                                   | -                                    | -                                   | -                                    | 1/45/0  | 1/45/0   |
| LU   | Latch-up                              | (per JESD78)                         | 1/6/0                               | 1/6/0                                | 1/6/0                               | 1/6/0                                | 1/6/0   | 1/6/0  |
| PC   | Automotive<br>Preconditioning Level 1 | (Level 1-260C)                       | -                                   | -                                    | -                                   | -                                    | No Fails  | No Fails   |
| тс   | Temperature Cycle, -<br>65/150C       | 500 Cycles                           | -                                   | -                                    | -                                   | -                                    | 1/77/0  | 1/77/0   |

| Туре | Test Name / Condition | Duration | Qual Device:<br><u>SN74HC541PWR</u> | Qual Device:<br><u>SN74HC573APWR</u> | Qual Device:<br><u>SN74HC574PWR</u> | Qual Device:<br><u>SN74HCT573PWR</u> | QBS Process<br>Reference:<br><u>SN74HC S273QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HC S244QPWRQ1</u> |
|------|-----------------------|----------|-------------------------------------|--------------------------------------|-------------------------------------|--------------------------------------|---|---|
| WBP  | Wire Bond Pull        | Wires    | -                                   | -                                    | -                                   | -                                    | 1/30/0  | 1/30/0  |
| WBS  | Wire Bond Shear       | Wires    | -                                   | -                                    | -                                   | -                                    | 1/30/0  | 1/30/0  |

QBS: Qual <u>By</u> Similarity
 Qual Device SN74HC241PWR is qualified at LEVEL1-260C
 Qual Device SN74HC574PWR is qualified at LEVEL1-260C
 Qual Device CD74HC377PWR is qualified at LEVEL1-260C
 Qual Device SN74HC373PWR is qualified at LEVEL1-260C

Qual Device SN74HC210PWR is qualified at LEVEL1-260C
 Qual Device SN74HC240PWR is qualified at LEVEL1-260C
 Qual Device SN74HC573PWR is qualified at LEVEL1-260CG
 Qual Device SN74HC273PWR is qualified at LEVEL1-260CG
 Qual Device SN74HC273PWR is qualified at LEVEL1-260CG

Qual Device SN74HC374PWR is qualified at LEVEL1260C
 Qual Device SN74HC374PWR is qualified at LEVEL1260C
 Qual Device SN74HC541PWR is qualified at LEVEL1260C

- Qual Device SN74HC573APWR is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green



## Approve Date 14-Sep-2021

# Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name /<br>Condition       | Duration    | Qual<br>Device:<br><u>SN74HC273N</u> | QBS Product<br>Reference:<br><u>CD74HC377PWR</u> | QBS Product<br>Reference:<br><u>SN74HC240PWR</u> | QBS Product<br>Reference:<br><u>SN74HC241PWR</u> | QBS Product<br>Reference:<br><u>SN74HC273PWR</u> | QBS Product<br>Reference:<br><u>SN74HC373PWR</u> | QBS Product<br>Reference:<br><u>SN74HC374PWR</u> |
|------|--------------------------------|-------------|--------------------------------------|--|--|--|--|--|--|
| CDM  | ESD - CDM                      | 1500 V      | 1/3/0                                | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
| HBM  | ESD - HBM                      | 5000V       | -                                    | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
| LU   | Latch-up                       | (Per JED78) | -                                    | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  |
| тс   | Temperature<br>Cycle, -65/150C | 500 Cycles  | 1/77/0                               | -  | -  | -  | -  | -  | -  |

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name /<br>Condition          | Duration                       | QBS Product<br>Reference:<br><u>SN74HC540PWR</u> | QBS Product<br>Reference:<br><u>SN74HC541PWR</u> | QBS Product<br>Reference:<br><u>SN74HC573APWR</u> | QBS Product<br>Reference:<br><u>SN74HC574PWR</u> | QBS Product<br>Reference:<br><u>SN74HCT573PWR</u> | QBS Process<br>Reference:<br><u>SN74HC S273QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HCT540N</u> |
|------|-----------------------------------|--------------------------------|--|--|---|--|---|---|---|
| AC   | Autoclave 121C                    | 96 Hours                       | -  | -  | -   | -  | -   | 1/77/0  | 3/231/0   |
| CDM  | ESD - CDM                         | 1500 V                         | 1/3/0  | 1/3/0  | 1/3/0   | 1/3/0  | 1/3/0   | 1/3/0   | -   |
| EC   | Electrical<br>Characterization    | Per<br>Datasheet<br>Parameters | -  | -  | -   | -  | -   | Pass  | -   |
| HAST | Biased HAST,<br>130C/85%RH        | 96 Hours                       | -  | -  | -   | -  | -   | 1/77/0  | -   |
| HBM  | ESD - HBM                         | 5000V                          | 1/3/0  | 1/3/0  | 1/3/0   | 1/3/0  | 1/3/0   | 1/3/0   | -   |
| HTOL | Life Test, 150C                   | 300 Hours                      | -  | -  | -   | -  | -   | 1/77/0  | -   |
| HTSL | High Temp<br>Storage Bake<br>150C | 1000 Hours                     | -  | -  | -   | -  | -   | 1/45/0  | -   |

| Туре | Test Name /<br>Condition          | Duration           | QBS Product<br>Reference:<br><u>SN74HC540PWR</u> | QBS Product<br>Reference:<br><u>SN74HC541PWR</u> | QBS Product<br>Reference:<br><u>SN74HC573APWR</u> | QBS Product<br>Reference:<br><u>SN74HC574PWR</u> | QBS Product<br>Reference:<br><u>SN74HCT573PWR</u> | QBS Process<br>Reference:<br><u>SN74HC S273QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HCT540N</u> |
|------|-----------------------------------|--------------------|--|--|---|--|---|---|---|
| HTSL | High Temp<br>Storage Bake<br>170C | 420 Hours          | -  | -  | -   | -  | -   | -   | 3/231/0   |
| LU   | Latch-up                          | (Per<br>JESD78)    | 1/6/0  | 1/6/0  | 1/6/0   | 1/6/0  | 1/6/0   | 1/6/0   | -   |
| PC   | Preconditioning<br>Level 1        | (Level 1-<br>260C) | -  | -  | -   | -  | -   | No Fails  | No Fails  |
| TC   | Temperature<br>Cycle, -65/150C    | 500 Cycles         | -  | -  | -   | -  | -   | 1/77/0  | 3/231/0   |

### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition       | Duration   | QBS Package Reference:<br><u>TPA3122D2N</u> | QBS Package Reference:<br><u>UC3875N</u> |
|------|-----------------------------|------------|---|--|
| AC   | Autoclave 121C              | 96 Hours   | 3/231/0                                     | 3/231/0                                  |
| HTSL | High Temp Storage Bake 170C | 420 Hours  | 3/231/0                                     | 3/231/0                                  |
| TC   | Temperature Cycle, -65/150C | 500 Cycles | 3/231/0                                     | 3/231/0                                  |

- QBS: Qual By Similarity - Qual Device SN74HC273N is qualified at LEVEL1-260C

Qual Device SN74HC273N is qualified at LEVEL1-260C
 Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TESL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1b Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
 Green/Pb-free Status:
 Qualitied Pb-Free(SMT) and Green



# Qualification Report Gatorade Expansion 16 pin PDIP SN74HC138, CD74HC138 SN74HC595, SN74HC139, SN74HC151, SN74HC157 SN74HC165, SN74HC166, SN74HC174, CD74HC237 CD74HC238, SN74HC251, CD74HC259, SN74HC259, SN74HC367

## Approve Date 09-Jul-2021

#### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Тур<br>е | Test Name<br>/ Condition        | Duration                                    | Qual<br>Device:<br><u>SN74HC595</u><br><u>N</u> | QBS Product<br>Reference:<br><u>SN74HCS137QPWRQ</u><br><u>1</u> | QBS Product<br>Reference:<br><u>SN74HCS138QPWRQ</u><br><u>1</u> | QBS Product<br>Reference:<br><u>SN74HCS139QPWRQ</u><br><u>1</u> | QBS Product<br>Reference:<br><u>SN74HCS151QPWRQ</u><br><u>1</u> | QBS Product<br>Reference:<br><u>SN74HCS157QPWRQ</u><br><u>1</u> | QBS Product<br>Reference:<br><u>SN74HC S165QDRQ</u><br><u>1</u> |
|----------|---------------------------------|---|---|---|---|---|---|---|---|
| ED       | Electrical<br>Distribution<br>s | Cpk>1.6<br>7 Room,<br>hot, and<br>cold test | -   | 1/30/0  | 1/30/0  | 1/30/0  | 1/30/0  | 1/30/0  | 1/30/0  |
| CDM      | ESD - CDM                       | 1500V                                       | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   |
| HBM      | ESD - HBM                       | 7000V                                       | -   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   | 1/3/0   |
| LU       | Latch-up                        | (Per<br>AEC-<br>Q100-<br>004)               | -   | 1/6/0   | 1/6/0   | 1/6/0   | 1/6/0   | 1/6/0   | 1/6/0   |

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Typ<br>e | Test Name<br>/<br>Condition     | Duratio<br>n                                | QBS Product<br>Reference:<br><u>SN74HCS166QDR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S174QPWR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S237QPWR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S238QPWR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S251QPWR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S259QPWR</u><br><u>Q1</u> | QBS Product<br>Reference:<br><u>SN74HC S367QPWR</u><br><u>Q1</u> |
|----------|---------------------------------|---|--|--|--|--|--|--|--|
| ED       | Electrical<br>Distribution<br>s | Cpk>1.6<br>7 Room,<br>hot, and<br>cold test | 1/30/0   | 1/30/0   | 1/30/0   | 1/30/0   | 1/30/0   | 1/30/0   | 1/30/0   |
| CD<br>M  | ESD -<br>CDM                    | 1500V                                       | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
| HB<br>M  | ESD -<br>HBM                    | 7000V                                       | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  | 1/3/0  |
| LU       | Latch-up                        | (Per<br>AEC-<br>Q100-<br>004)               | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  | 1/6/0  |

## Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре  | Test Name / Condition          | Duration                             | QBS Product<br>Reference:<br><u>SN74HC S595QPWRQ1</u> | QBS Process<br>Reference:<br><u>SN74HC S74QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HC595N</u> | QBS Package<br>Reference:<br><u>TLV9054IDR</u> |
|-------|--------------------------------|--------------------------------------|---|--|--|--|
| ED    | Electrical Characterization    | Per Datasheet Parameters             | -   | -  | Pass   | 1/30/0   |
| ED    | Electrical Distributions       | Cpk>1.67 Room, hot, and cold<br>test | 3/90/0  | 3/90/0   | -  | -  |
| CDM   | ESD - CDM                      | 1500V                                | -   | 1/3/0  | -  | 1/3/0  |
| CDM   | ESD - CDM                      | 2000V                                | 1/3/0   | -  | -  | -  |
| HBM   | ESD - HBM                      | 4000V                                | -   | -  | -  | 1/3/0  |
| HBM   | ESD - HBM                      | 9000V                                | 1/3/0   | -  | -  | -  |
| HBM   | ESD - HBM                      | 7000V                                | -   | 1/3/0  | -  | -  |
| LU    | Latch-up                       | (Per AEC-Q100-004)                   | 1/6/0   | 1/6/0  | -  | 1/6/0  |
| ELFR  | Early Life Failure Rate, 125C  | 48 Hours                             | -   | 3/2400/0   | -  | -  |
| HTOL  | Life Test, 150C                | 300 Hours                            | 1/77/0  | 3/231/0  | -  | 1/77/0   |
| UHAST | Unbiased HAST<br>130C/85%RH    | 96 Hours                             | -   | -  | -  | 3/231/0  |
| AC    | Autoclave 121C                 | 96 Hours                             | 1/77/0  | 3/231/0  | 3/225/0  | -  |
| HAST  | Biased HAST, 130C/85%RH        | 96 Hours                             | 1/77/0  | 3/231/0  | -  | 3/231/0  |
| HTSL  | High Temp Storage Bake<br>150C | 1000 Hours                           | 1/45/0  | 3/135/0  | -  | -  |

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| Туре | Test Name / Condition           | Duration   | QBS Product<br>Reference:<br><u>SN74HC S595QPWRQ1</u> | QBS Process<br>Reference:<br><u>SN74HCS74QPWRQ1</u> | QBS Package<br>Reference:<br><u>SN74HC595N</u> | QBS Package<br>Reference:<br><u>TLV9054IDR</u> |
|------|---------------------------------|------------|---|---|--|--|
| HTSL | High Temp Storage Bake<br>170C  | 420 Hours  | -   | -   | 3/231/0  | 3/231/0  |
| TC   | Temperature Cycle, -<br>65/150C | 500 Cycles | 1/77/0  | 3/231/0   | 3/231/0  | 3/231/0  |

- OBS: Qual By Similarity

- Qual Device SN74HC595N is qualified at Not Classified

- The following was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb\_free Status:

Qualified Pb-Free(SMT) and Green



TI Information Selective Disclosure

## **Qualification Report**

## Gatorade Expansion 16 Pin PDIP SN74HC138N, CD74HC138N, SN74HC595N, SN74HC139N, SN74HC151N, SN74HC157N, SN74HC165N, SN74HC166N, SN74HC174N, CD74HC237N, CD74HC238N, SN74HC251N, CD74HC259N, SN74HC259N, SN74HC367N

#### Approve Date 21-Jul-2021

#### Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

| Туре | Test Name / Condition          | Duration           | Qual<br>Device:<br><u>SN74HC138N</u> | QBS Product<br>Reference:<br><u>SN74HCS16507QDRQ1</u> | QBS<br>Product/Process<br>Reference:<br><u>SN74HC S74QPWRQ1</u> | QBS Process<br>Reference:<br><u>SN74HC S595QPWRQ1</u> | QBS Package<br>Reference:<br>L293DNE | QBS<br>Package<br>Reference:<br><u>SN74HC00N</u> |
|------|--------------------------------|--------------------|--------------------------------------|---|---|---|--------------------------------------|--|
| EC   | Electrical Characterization    | Cpk>1.67           | -                                    | 1/30/0  | 3/90/0  | -   | -                                    | -  |
| CDM  | ESD - CDM                      | 1500 V             | -                                    | 1/3/0   | 1/3/0   | -   | -                                    | -  |
| HBM  | ESD - HBM                      | 7000 V             | -                                    | 1/3/0   | 1/3/0   | -   | -                                    | -  |
| LU   | Latch-up                       | (Per AEC-Q100-004) | -                                    | 1/6/0   | 1/6/0   | -   | -                                    | -  |
| ELFR | Early Life Failure Rate, 125C  | 48 Hours           | -                                    | -   | 3/2400/0  | -   | -                                    | -  |
| HTOL | Life Test, 150C                | 300 Hours          | -                                    | -   | 3/231/0   | 1/77/0  | -                                    | -  |
| AC   | Autoclave 121C                 | 96 Hours           | -                                    | -   | 3/231/0   | 1/77/0  | 3/231/0                              | -  |
| HAST | Biased HAST, 130C/85%RH        | 96 Hours           | -                                    | -   | 3/231/0   | 1/77/0  | -                                    | 1/77/0   |
| HTSL | High Temp Storage Bake<br>150C | 1000 Hours         | -                                    | -   | 3/135/0   | 1/45/0  | -                                    | -  |
| HTSL | High Temp Storage Bake<br>170C | 420 Hours          | -                                    | -   | -   | -   | 3/231/0                              | -  |
| TC   | Temperature Cycle, -65/150C    | 500 Cycles         | -                                    | -   | 3/231/0   | 1/77/0  | 3/225/0                              | 1/77/0   |
| WBP  | Wire Bond Pull                 | Wires              | 1/76/0                               | -   | -   | -   | -                                    | -  |
| WBS  | Wire Bond Shear                | Wires              | 1/76/0                               | -   | 3/231/0   | -   | -                                    | -  |

- QBS: Qual By Similarity

- Qual Device SN74HC138N is qualified at LEVEL1-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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